

Overview of the Calorimeter Readout Upgrades

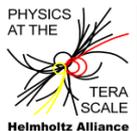
A. Straessner
on behalf the ATLAS and CMS Calorimeter Upgrade Groups



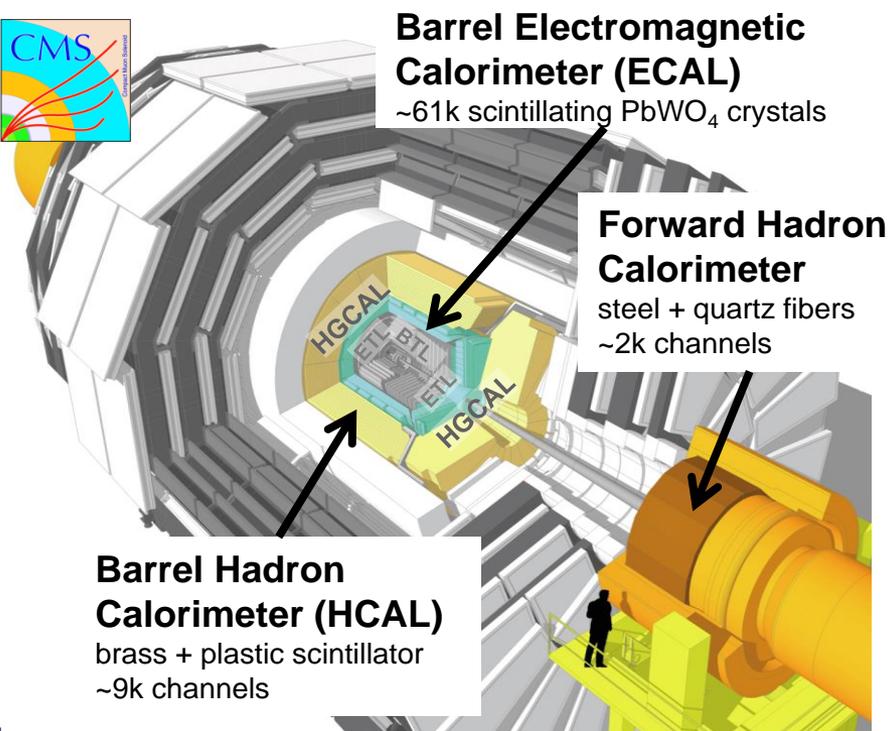
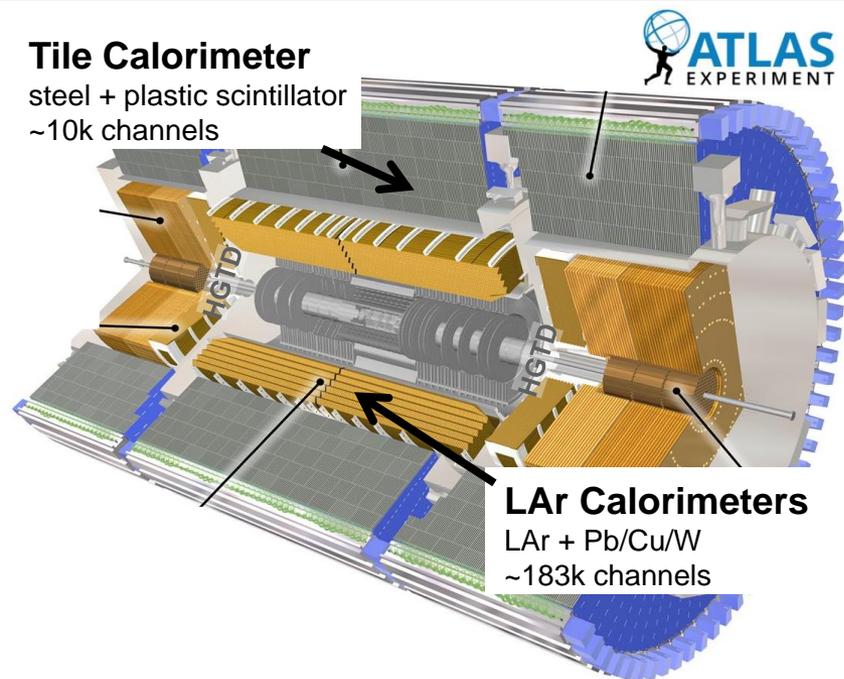
ACES 2018
CERN
April 24-26, 2018



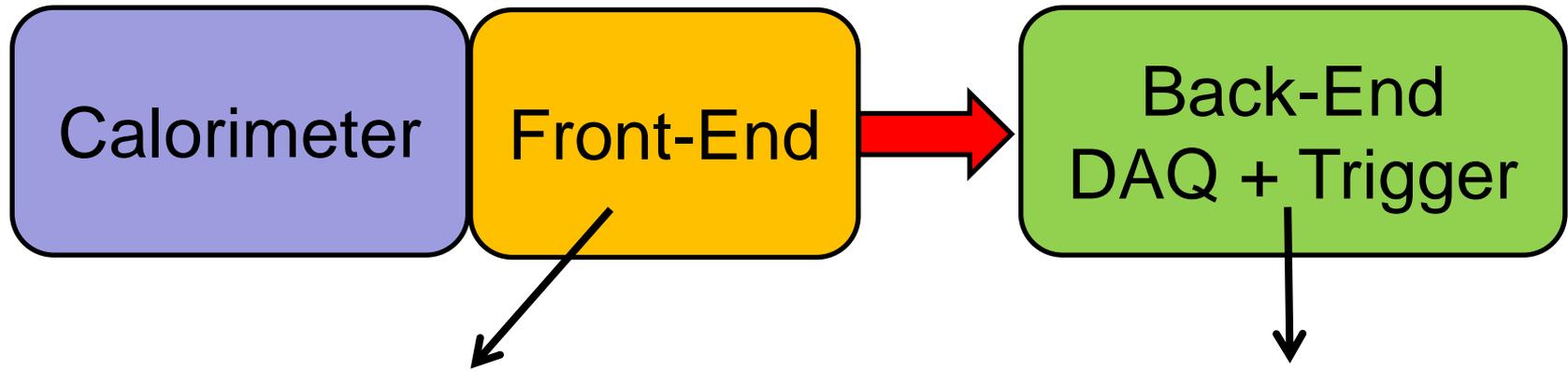
Bundesministerium
für Bildung
und Forschung



General Concepts



- Motivation for calorimeter electronics upgrade:
 - Higher trigger rate of 0.75 - 1 MHz and larger event buffers (> 10 μ s)
→ improved trigger system for high pile-up
 - Improved radiation tolerance (2-10 kGy) and system longevity - where necessary
 - Improved timing measurement - where possible
- General concept: move buffers and pipelines off detector and read out at 40 MHz
- New additional timing detectors: Lindsay Gray Tuesday 16h30
- New CMS high-granularity endcap calorimeter: Paul Rubinov Wednesday 14h30



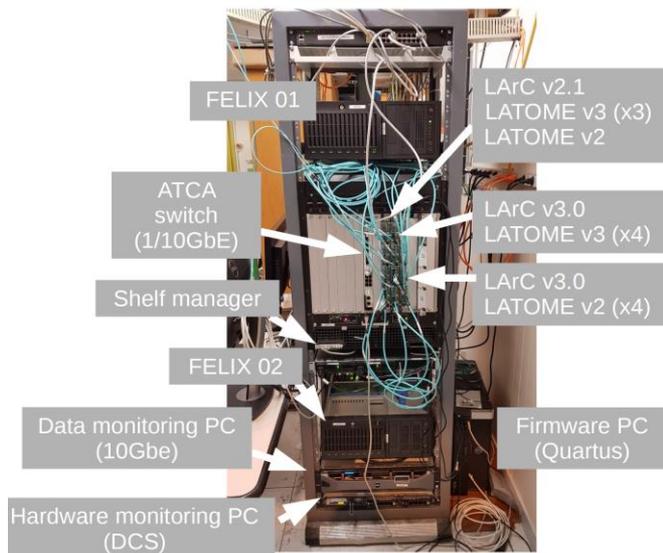
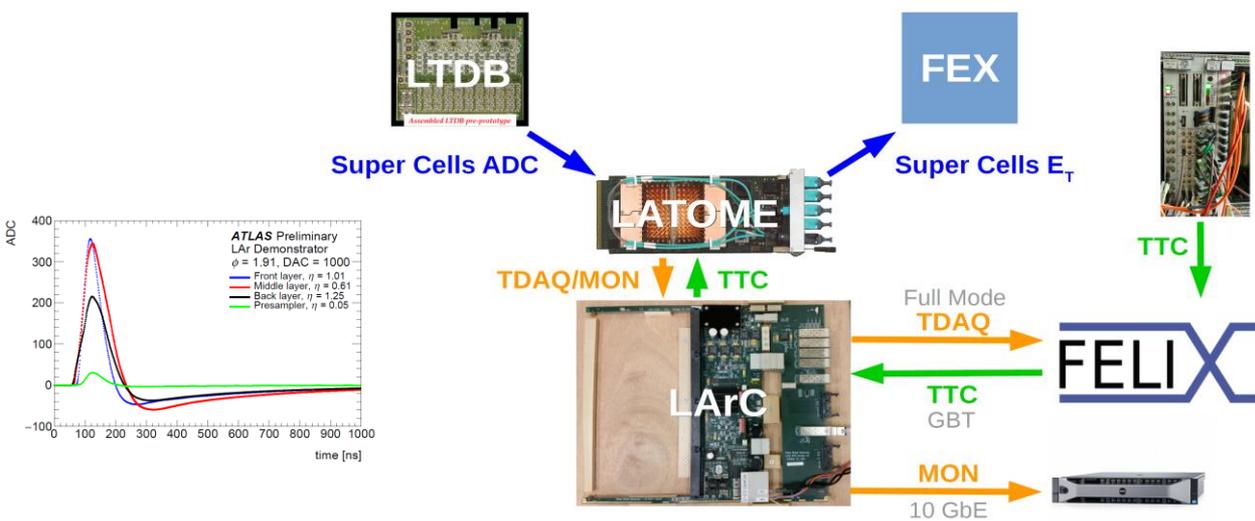
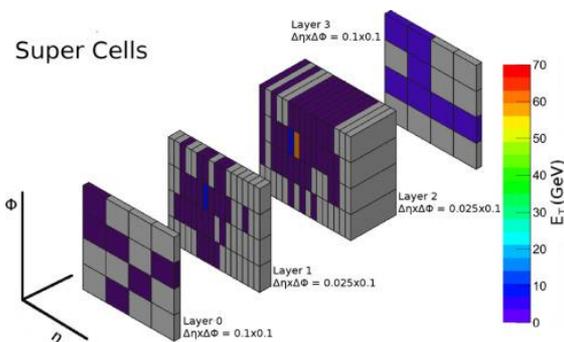
- Radiation tolerant ASICs and Commercial-Off-The-Shelf (COTS) components:
 - signal amplification and shaping
 - ADCs, TDCs
 - optical links with 5-10 Gbps
- Trigger, Timing and Control (TTC) distribution
- Power distribution for HV and LV

- High-bandwidth, low-latency signal processing with FPGAs
- Data buffering in FPGAs or on-board memory
- High-bandwidth interfaces to hardware trigger and to network based trigger/DAQ systems

Phase-0/I Upgrades

LHC Long-Shutdown 2: 2019-2020

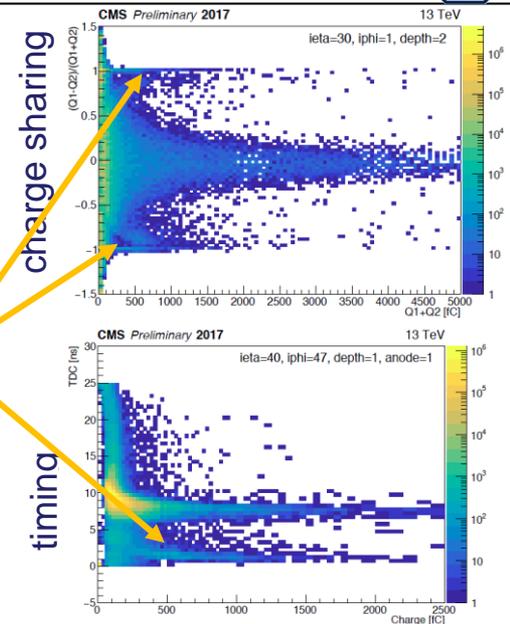
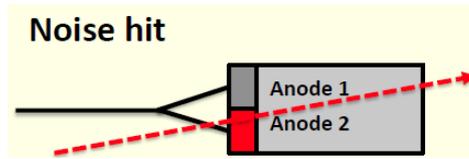
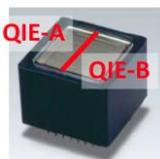
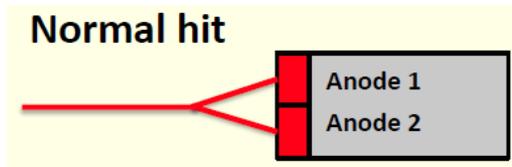
- 124 LAr Trigger Digitizer Boards on front-end to read out new supercell trigger primitives
 - COTS analog components
 - ASICs: 130 nm CMOS 4-bit pipeline + 8-bit SAR ADC, 250 nm Si-on-Sapphire link-on-chip
- 31 LAr Digital Processing Blades for signal filtering, energy calculation, data buffering
 - ATCA carrier blades equipped with 4 FPGA advanced mezzanine cards



- Board production is being prepared - installation and commissioning in LS2
- Complex installation: removal of all front-end boards and installation of new baseplane
- System will remain during HL-LHC running

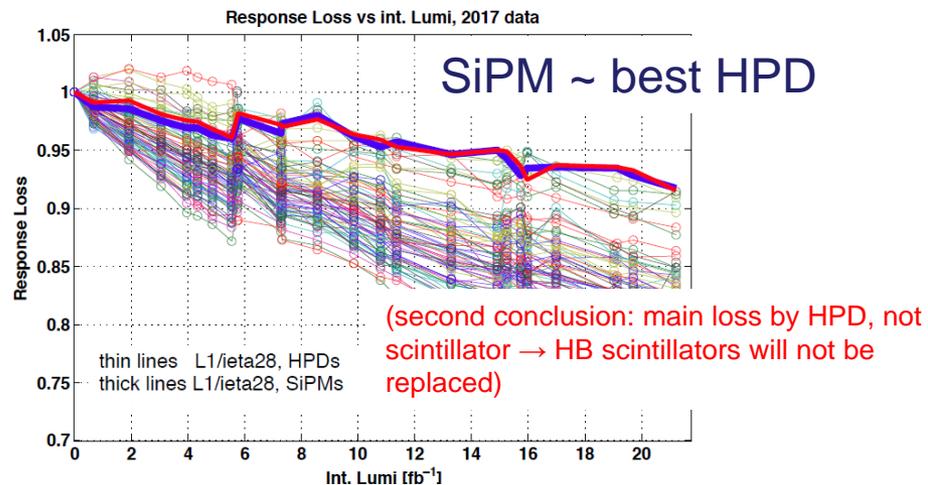
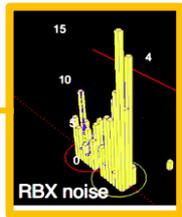
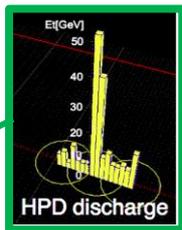
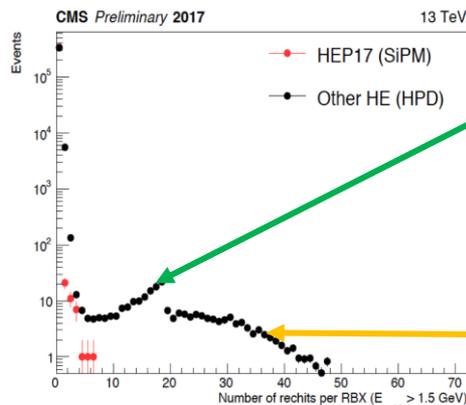
- Forward HCAL upgrade in LS 1 → reduce noise hits

- new MAPMT
 - QIE10 (8-bit ADC 17 bit dyn. range, 6-bit TDC)
 - μ TCA back-end
- } stays for HL-LHC



- Endcap HCAL → reduce noise and mitigate HPD damage

- SiPMs replace Hybrid Photo Diodes (HPD)
- QIE11 (programmable gain, low impedance)
- demonstrator run in 2017 → full HE already upgraded in shutdown 2017/18



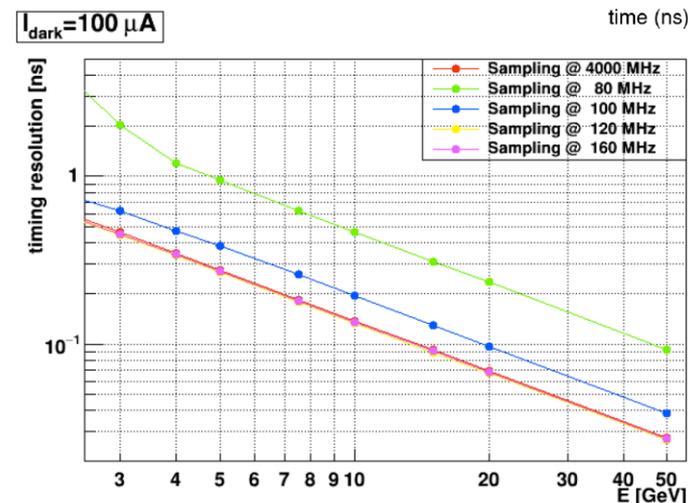
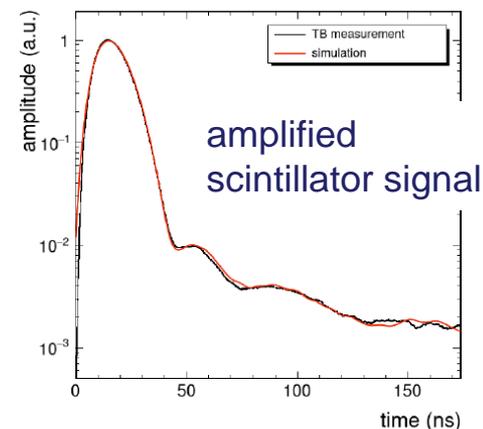
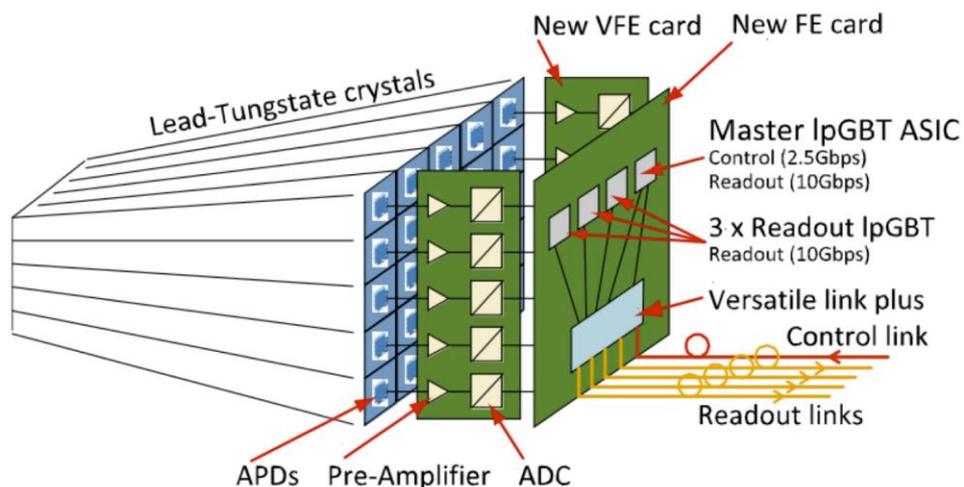
- full HB will be equipped in LS2
- HE will be replaced by HGCal in LS3

Phase-II Upgrades

LHC Long-Shutdown 3: 2024-2026

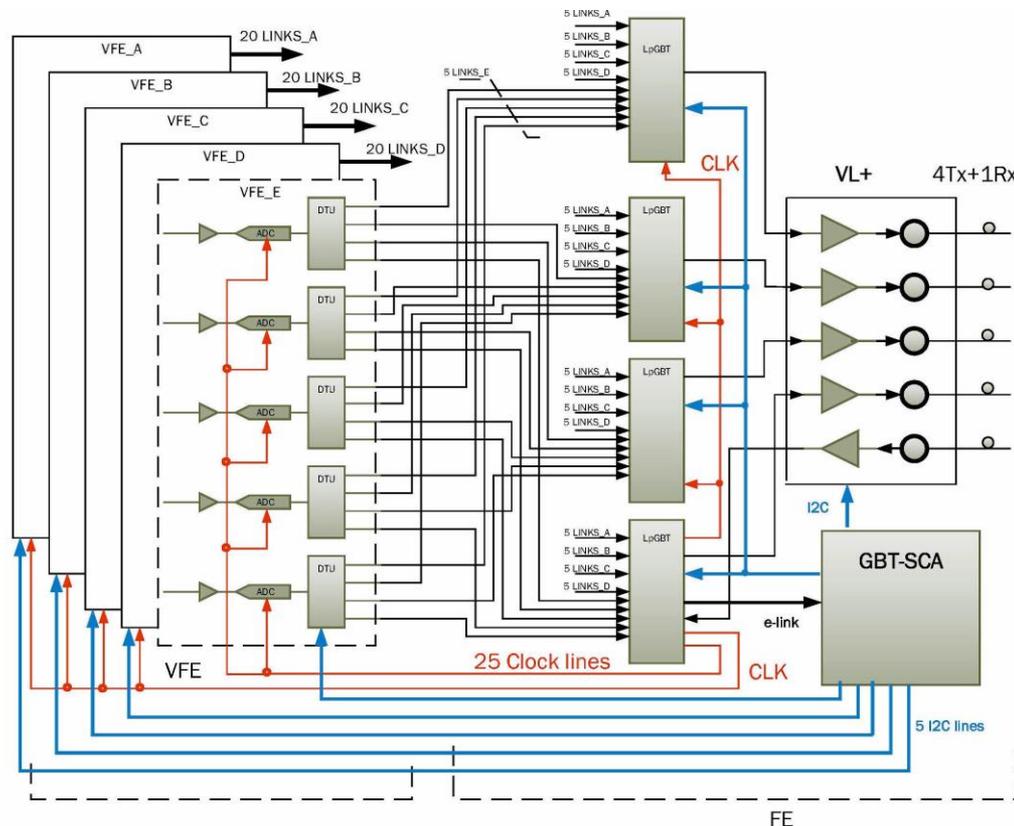
- APD light readout will remain, but new FE electronics
 - 80 MeV noise RMS; 50 MeV - 2 TeV dynamic range
 - 2 gains with two 12-bit ADCs per channel
 - 2‰ integral non-linearity
 - 30 ps electron time resolution @ 50 GeV and $\langle\mu\rangle=200$

- 12240 Very Front-End cards for 61200 channels



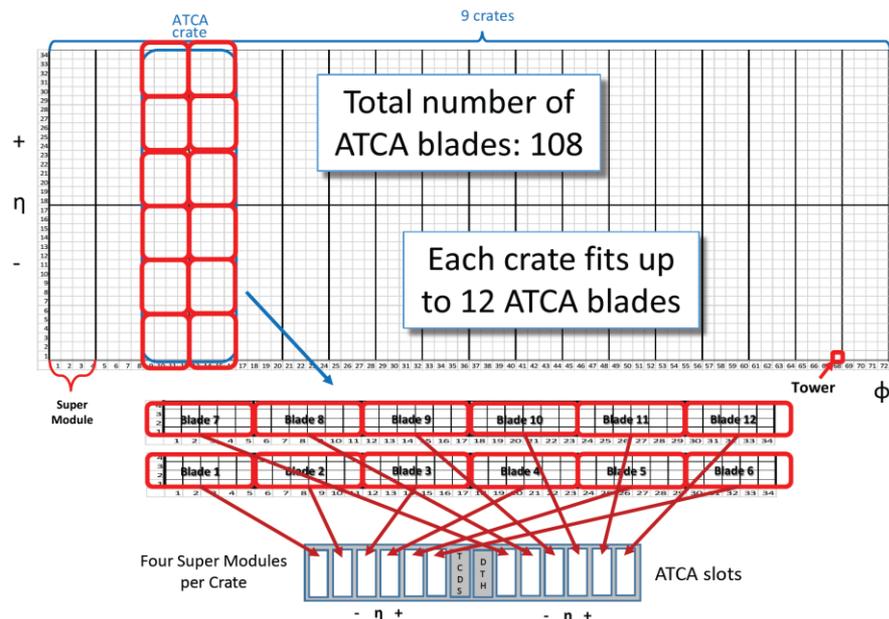
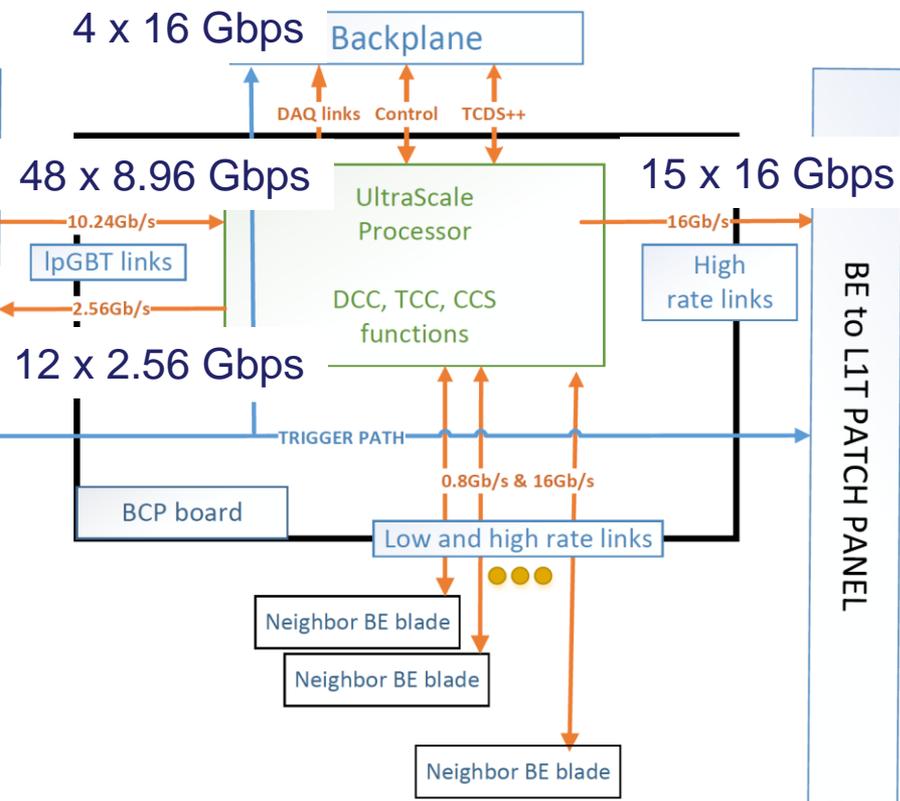
- Trans-impedance amplifier with low-pass in 130 nm TSMC:
 - about x3 improved timing resolution compared to CR-RC preamp-shaper (backup)
- ADC sampling rate 160 MHz optimal for time resolution and spike rejection
 - commercial ADC IP block integrated in dedicated ASIC in 65 nm TSMC

- 2448 Front-End cards transmit ADC data and distribute clock and control signals
- ADC data compression on statistical basis is being studied:
 - "long" data transfer for energies above ~ 6 GeV = 7 bit
 - only for a small fraction of events (10^{-4} - 10^{-5})



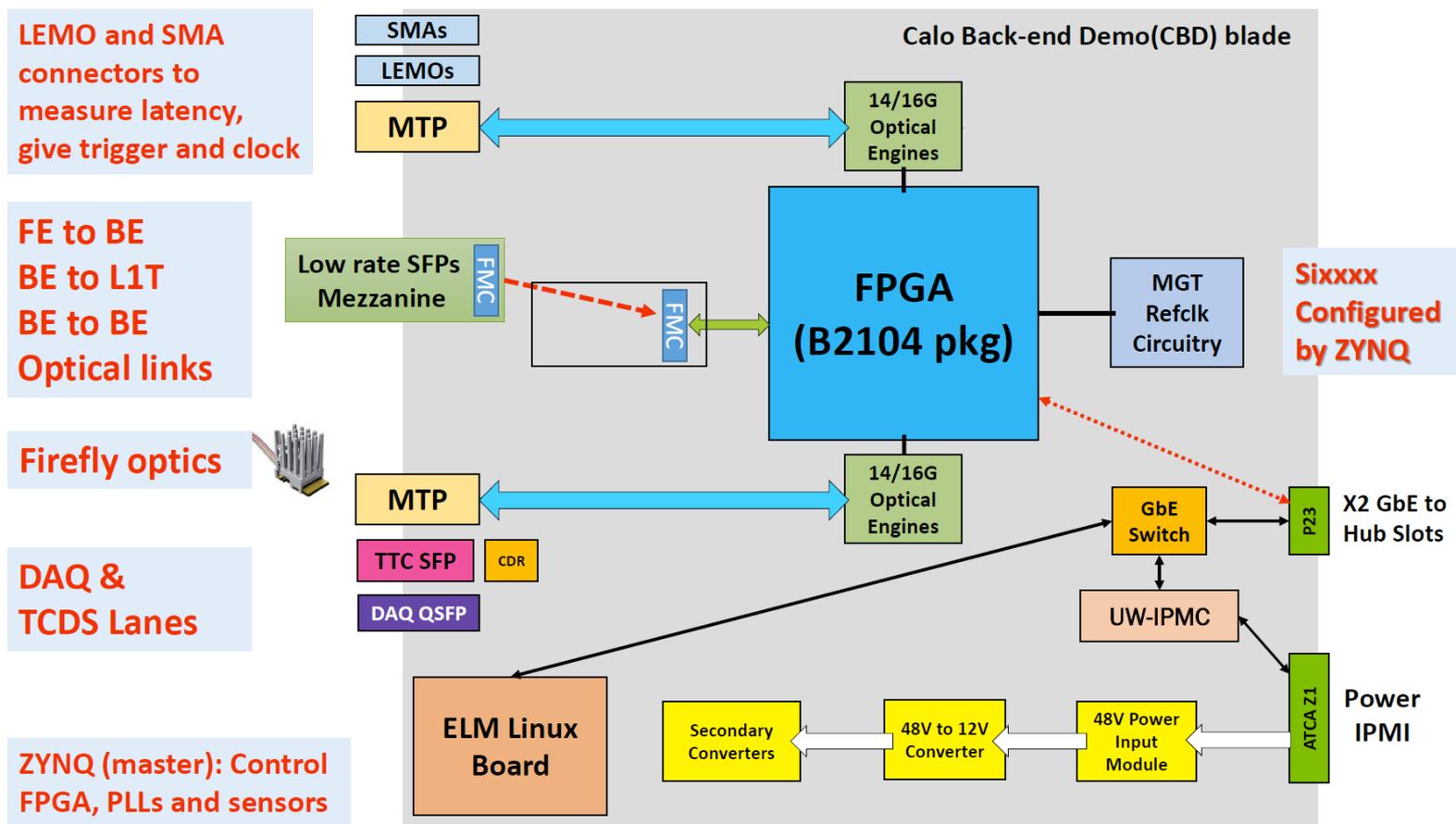
- Total data rate per FE card: $13 \text{ bit} \times 160 \text{ MHz} \times 25 = 52 \text{ Gbps}$
 → lossless data compression by factor 2 to fit into $4 \times 8.96 \text{ Gbps} = 4 \text{ IpGBT links}$
- Best compatible with 4 Tx + 1 Rx VL+ format

- Barrel Calorimeter Processor (BCP):
 - transverse energy calculation
 - trigger primitive preparation:
 - single crystal or cluster
 - anomalous pulse spike rejection
 - TTC distribution to/from FE



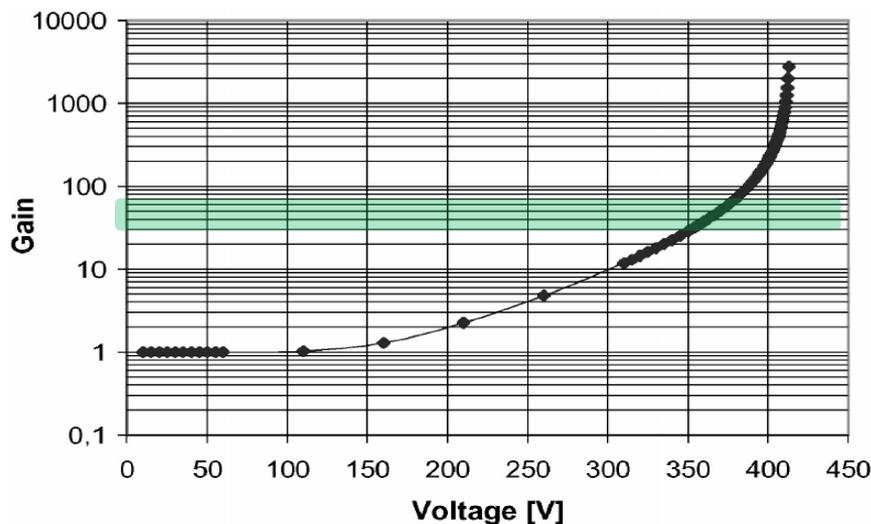
- 2 FPGAs per BCP
- 300 crystals per FPGA
- 15 x 16 Gbps for L1 trigger primitives (10 bit E_T , 1 bit spike, 5 bit time per crystal) \rightarrow 3060 trigger links total
- 43 kb / event for crystal readout with 20 samples + 8 kb / event for trigger primitives
- total DAQ bandwidth 4 x 16 Gbps / FPGA

- BCP demonstrator:
 - ATCA blade with 2 Xilinx Ultrascale FPGAs and SAMTEC Firefly transceivers
 - 2 ZYNQ FPGA mezzanines for board control, ATCA system interface and Embedded Linux Mezzanine



- New HV system for APD to cope with radiation damage after 3000 fb⁻¹
 - increased dark current to 100 μA expected and possible shorts of APD pairs
 - increased bias voltage by +30 V necessary

Parameter	Legacy HV system	HL-LHC HV system
Output voltage range	0–500 V	0–600 V
Programmable setting step	1 mV	1 mV
External calibration	±20 mV	±20 mV
DC regulation at load	±20 mV	±20 mV
DC stability at load (over 90 days)	±70 mV	±70 mV
Low freq. noise at load (f < 100 KHz)	±20 mV	±20 mV
High freq. noise at load (f > 100 KHz)	±20 mV	±20 mV
Operating temperature at supply	15–40 °C	15–40 °C
Current limit	15 mA	20 mA
On and off ramp rate	2–50 V/s	2–50 V/s
Current measurement (from 1μA)	5%	5%



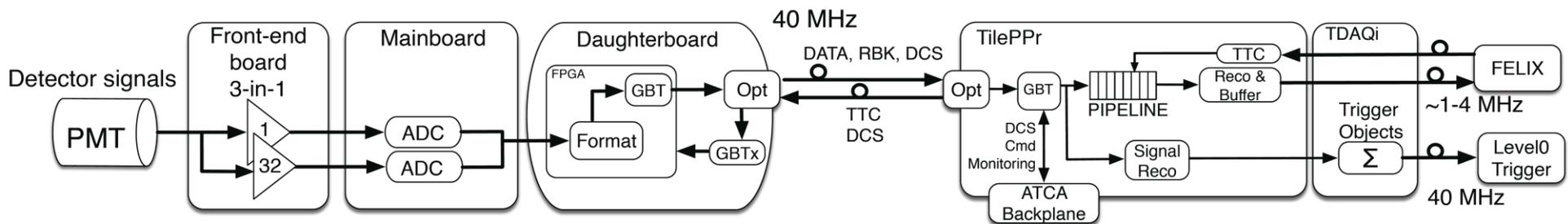
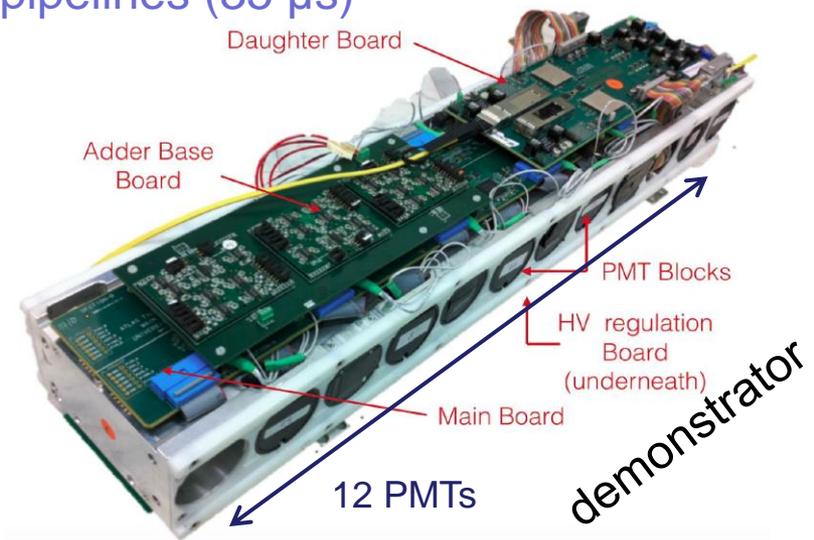
- 36 readout boxes x 252 channels = 9072 channels
- 36 x 32 optical links at 5 Gbps → 18 ATCA Barrel Calorimeter Processors (BCP)
 - 2 FPGAs per BCP prepare trigger primitives and readout data

Table 3. CMS Phase-2 detector projected data links and event size summary.

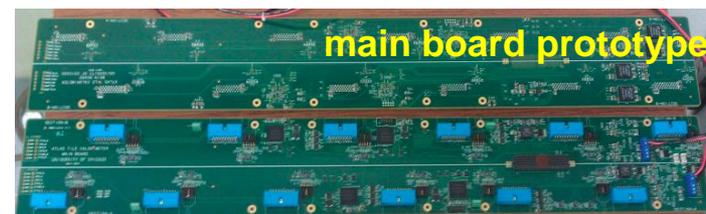
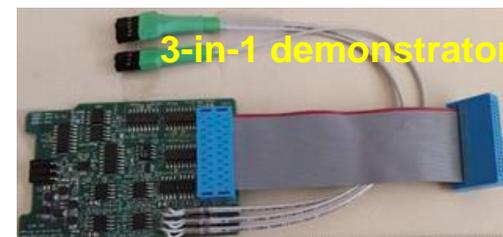
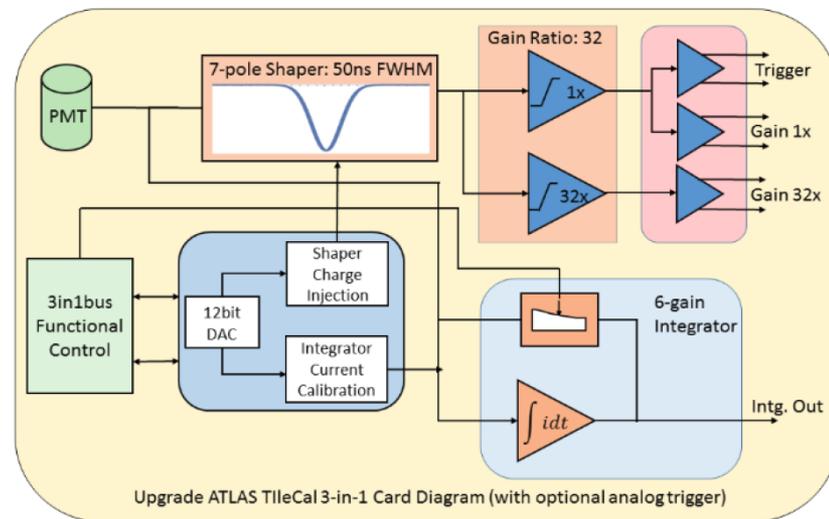
subdet	FE daq links	FE trigger links	sub-event size	BE leaf cards	BE crates	DAQ links	notes
PxTk	1000	0	1.6	100	12	48	
SiTk	1500	13500	0.5	300	33	132	(⁷)
ECAL	8000	2000	1.2	100	12	48	(⁸)
HCAL	1000	1000	0.2	100	12	48	(⁸)
HGCAL	8000	8000	1.2	160	18	72	
DT	0	3000	0.1	60	8	16	(⁹)
CSC	0	600	0.2	12	2	8	(⁹)
GEM	500	1000	0.05	30	12	12	
RPC	1000	1000	0.06	40	5	20	
Other	1000	1000	0.1	20	3	12	
Total	25612	27500	5.0	922	117	416	

- What will happen with HB μ TCA hardware?
 - Phase-I HB μ TCA boards will be used in in ATCA adapter boards to equip the Forward HCAL (HF)

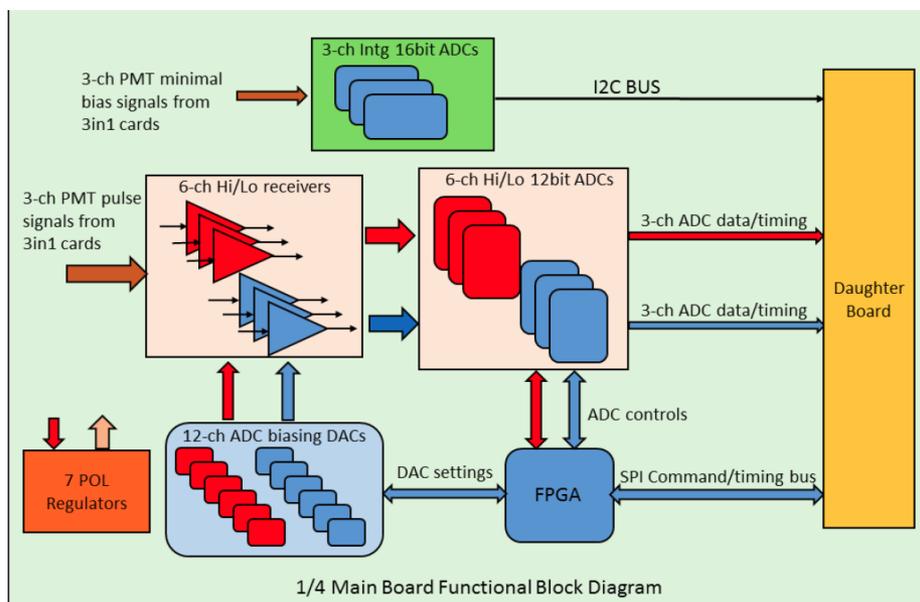
- Scintillator tiles will not be exchanged → upgrade of front-end and off-detector electronics to cope with
 - higher trigger rate (1-4 MHz), extended data pipelines (35 μs)
 - higher radiation levels
- New mini-drawer concept will allow better accessibility of electronics for maintenance
- Replacement of most radiation exposed PMTs
 - Hamamatsu R11187 more robust, higher quantum efficiency
 - 768 out of 9852 PMTs (8%) will be replaced
- Full calorimeter information will be read out at 40 MHz → full granularity trigger input



- Baseline: 3-in-1 front-end card on main board
- shaped and digitized PMT pulse for energy reconstruction:
 - 7-pole passive LC shaper
 - low-pass differential analog drivers
 - 2 gains for 17 bit dynamic range
- charge integration amplifier (10-21 ms) for Cs-source calibration and luminosity monitoring: digitized at 50 kHz with 16-bit ADC

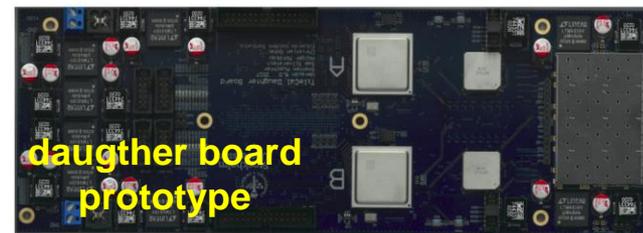


- Main board equipped with:
 - 12-bit COTS ADCs (LTC2264-12)
 - Altera Cyclone FPGA for control



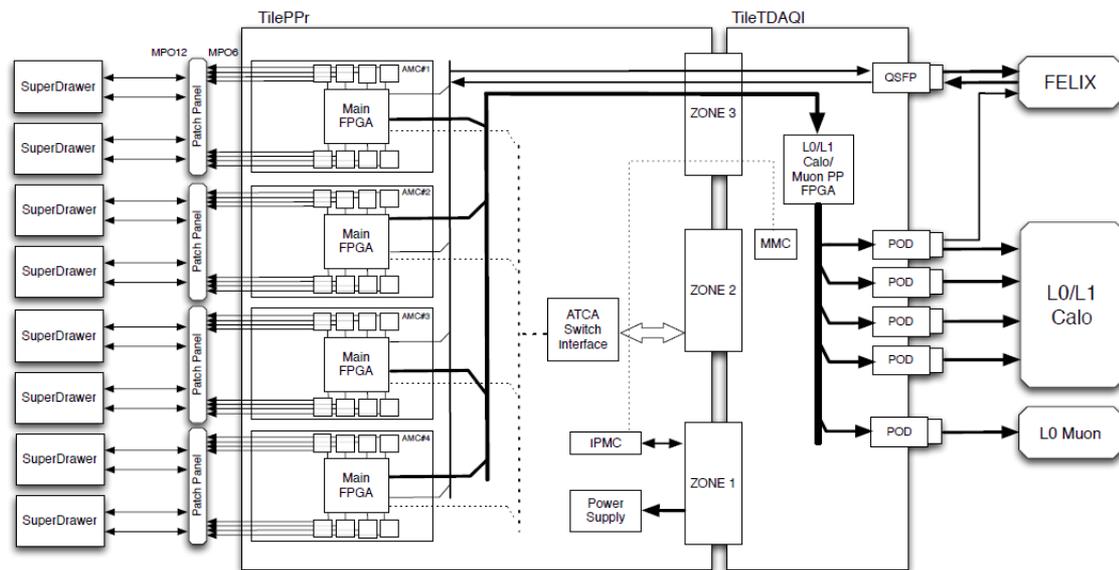
- Daughterboards on front-end:

- 2 Xilinx Kintex Ultrascale+ with triple redundant logic for serialisation
 - SEE tests to be done
 - tests with Kintex-7 show 1-2 non-recoverable errors per month at HL-LHC
- 2 SFPs for optical transmission at 9.6 Gbps with Forward Error Correction
- GBTx chip for clock and control

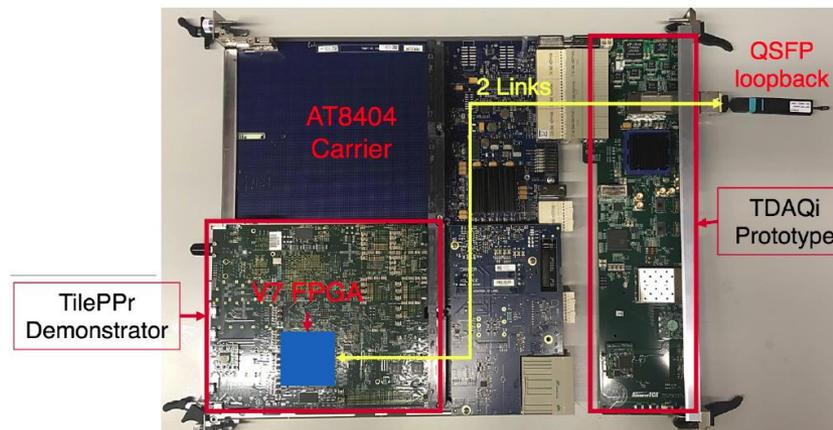


- Off-detector:

- Tile Preprocessor (PPr)
- Tile TDAQ interface (TDAQi)



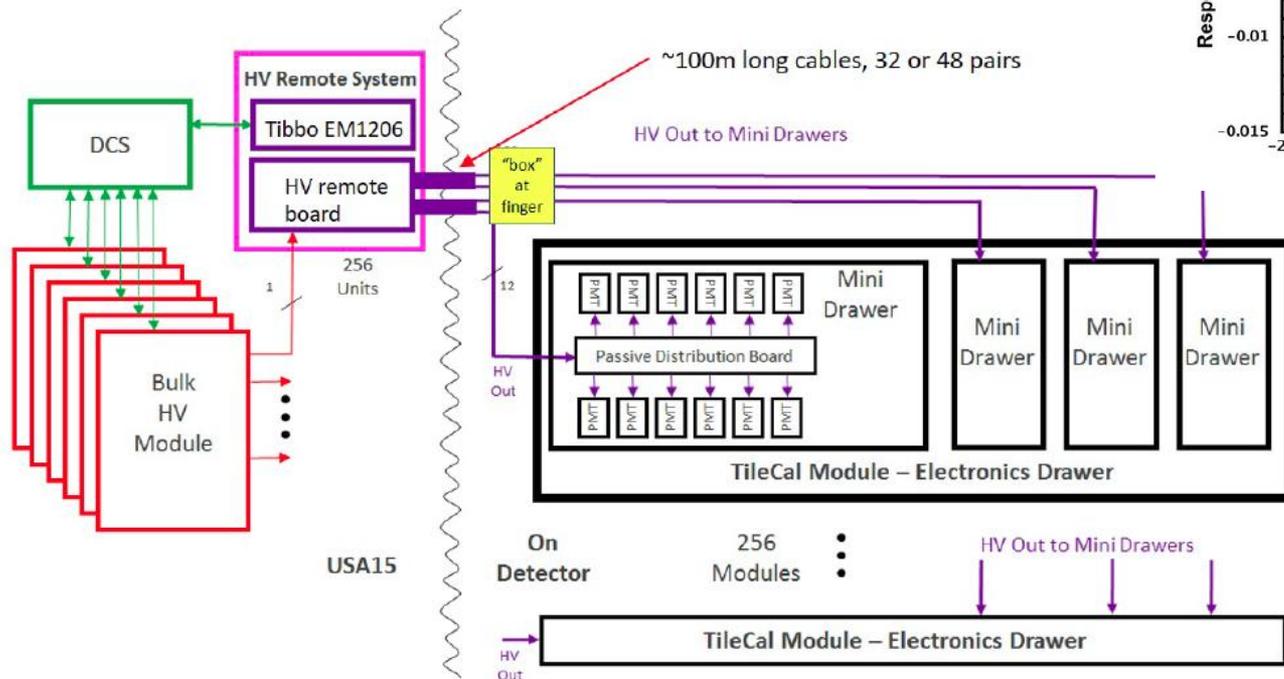
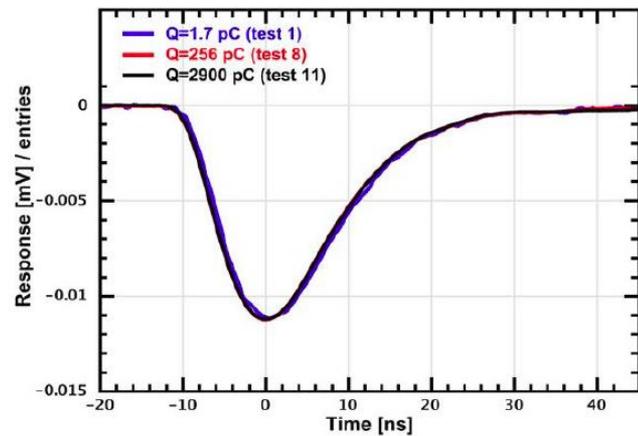
- 32 ATCA carrier blades each with 4 Compact Processor Modules (CPM)
- 4096 up-links at 9.6 Gbps and 2048 down-links at 4.8 Gbps
- CPM Advanced Mezzanine Card:
 - 32 input links / FPGA = 8 mini drawers
 - digital filter and energy reconstruction
 - 12 DSPs / channel
 - data buffering until L0/L1 accept
 - >2 Mbit memory
 - candidate FGPA Xilinx Kintex Ultrascale



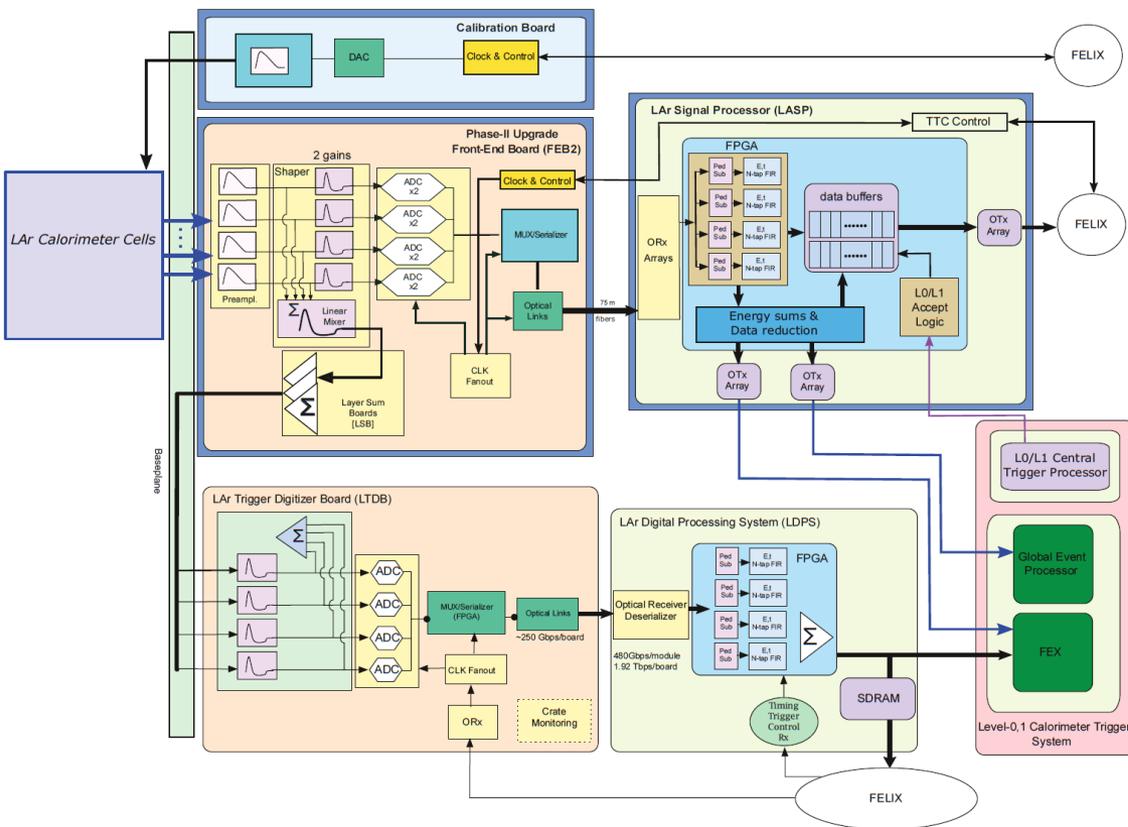
- TDAQi Rear Transition Module:
 - preparation of digital trigger sums → trigger Feature EXtractor (FEX) modules
 - full granularity data after noise threshold ($>2\sigma$) → Global Event trigger processors
 - D-layer cells for muon trigger reconstruction

	Receiver	Granularity ($\eta \times \phi$)	Number objects per PPr	Resolution	Link bandwidth	Available bits per link and BC	Bits per link used (data)	Objects per link	Link count
CALO	eFEX	0.1 x 0.1	192 TTs	13 bits	11.2 Gb/s	224	208	16	12
	jFEX	0.1 x 0.1	192 TTs	13 bits	11.2 Gb/s	224	208	16	12
	gFEX	0.2 x 0.2	16 TTs	13 bits	11.2 Gb/s	224	208	16	1
	Global		48 cells	15 bits	14.4 Gb/s	288	184	8	6
MUON	RPC	D-cells	40 cells	15 bits	11.2 Gb/s	224	210	14	3
	TGC	D-cells	36 cells	15 bits	11.2 Gb/s	224	180	12	3

- HV regulators moved to radiation-free environment, each PMT connected individually (100 m cable)
- active HV dividers, improved grounding scheme
- low HV ripple and noise (few mV RMS), stable HV



- Send all data off detector at 40 MHz → flexibility of the trigger system
 - accept rate 1-4 MHz, 35 μ s pipelines
 - full granularity calorimeter information available to trigger
- Preserve noise performance as today: non-linearity 2 ‰, detectable MIP signal
- Keep electroweak physics in same gain range (H,Z,W,...):
 - 2-gain readout and 14-bit ADC for 16-17 bit dynamic range

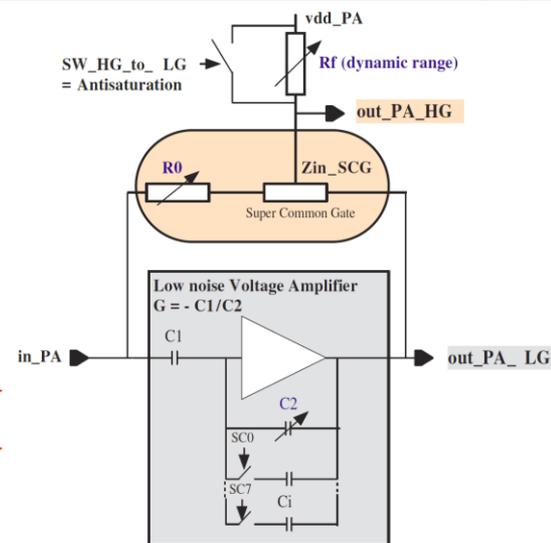
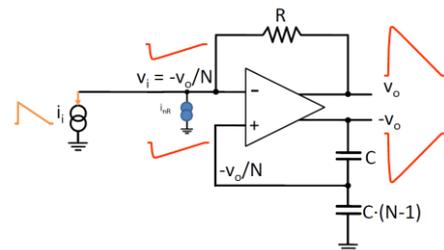


- 1524 new Front-end boards (1 FEB2 / 128 channels)
- 372 LAr Signal Processors (LASP)
- 130 electronic Calibration Boards
- New FE powering
- Phase-I supercell readout remains

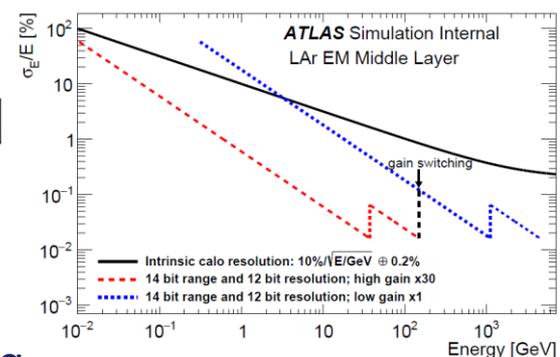
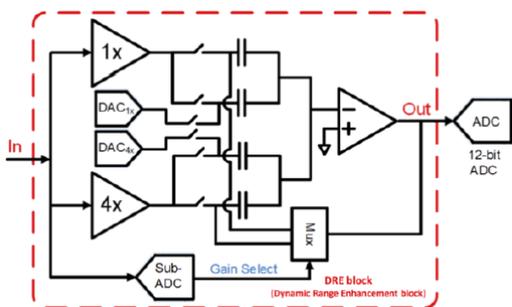
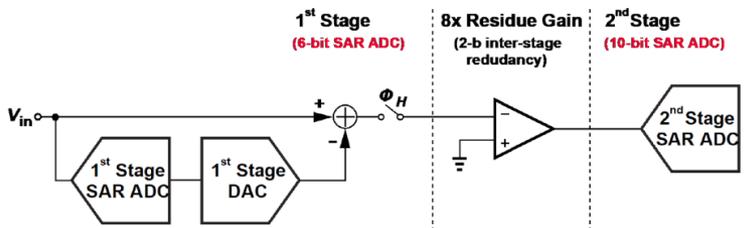
- Two preamplifier/shaper developments:
 - super common gate preamp in 130 nm TSMC
 - fully differential preamp/shaper in 65 nm
 - both have tunable input impedance and low noise
- combine strengths of the two SAR designs into new 130 nm chip

- CR-(RC)² shaping is still optimal at high pile-up

- Two ADC designs:
 - 12-bit SAR ADCs combined with Dynamic Range Enhancer (DRE) → 14-bit ADC



R0, C2 tuneable to set absolute value of Zin
 Ci: 8-bit fine adjustment of Zin (±5%) using Slow Control parameters



- commercial 12-bit ADC IP block (CMS) with oversampling and digital filter → 14-bit ADC

- 22 IpGBT Tx links per FEB2 for data transmission → 33528 fibers
- 2 IpGBT Tx/Rx link pairs per FEB2 for individual clock and control → 6096 fibers



Baseline links per FPGA:

- 88 lpGBT input links to process 512 cells
- 2-3 DAQ links, up to 27 links for trigger FEX
- 4 links for Global Event trigger @ 25 Gbps

Main tasks:

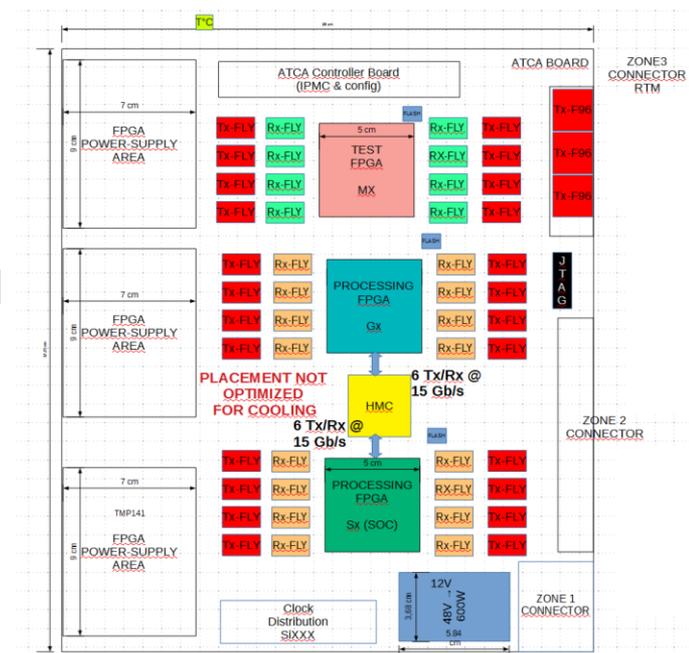
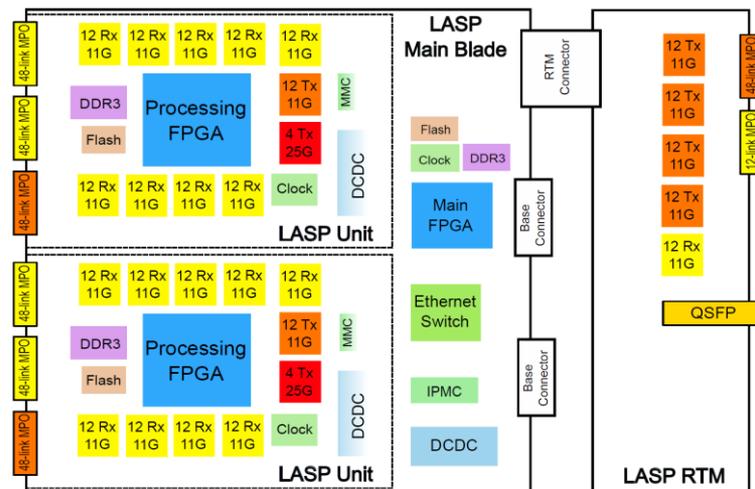
- digital signal filtering and energy+time measurement with active pile-up correction
- preparation of trigger primitives: energy sums and energy-ordered cell energies
- real-time baseline correction - if needed

→ 36 DSPs/channel and 151 Mbit of memory / FPGA

Ongoing R&D on full-size ATCA blades

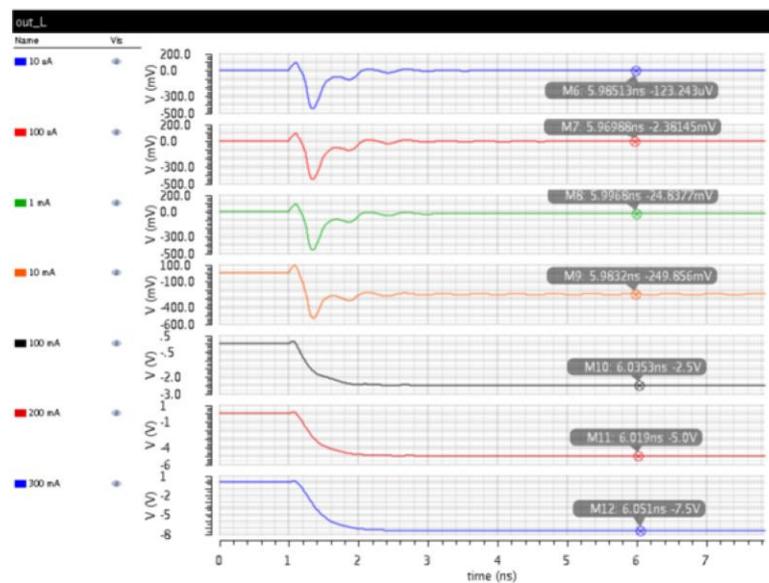
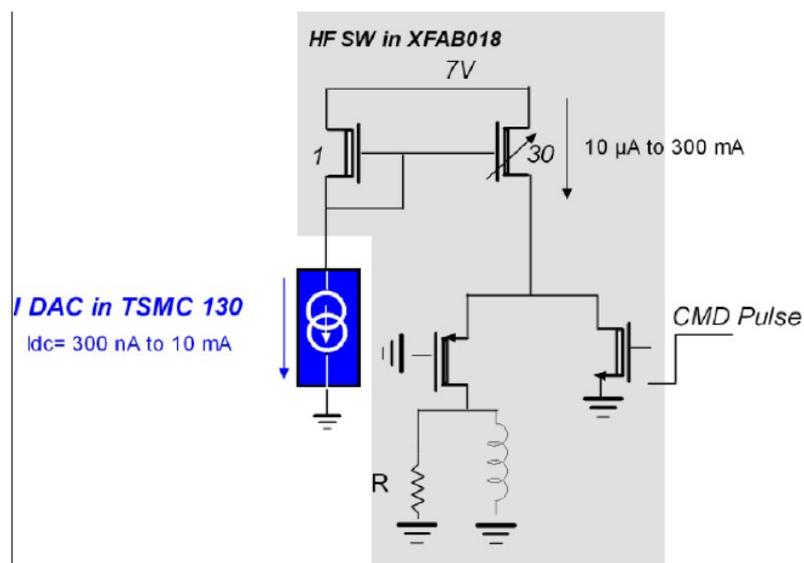
- evaluate Altera/Intel Stratix 10 SX / MX: integrated processor or large high-bandwidth memory
- Samtec Firefly transceivers
- cooling is a challenge

• TTC distribution to FEB2 → evaluate solution as separate TTC blade (less powerful FPGAs needed)



LASP Testboard

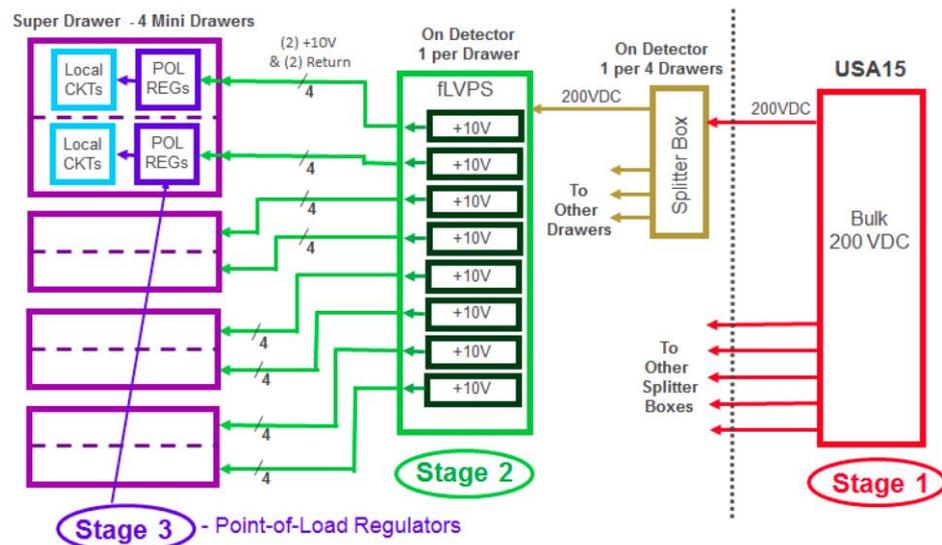
- Pulses are injected at the level of the LAr calorimeter electrodes
- To cover signal currents up to 10 mA, a 7.5 V calibration pulse needs to be injected → HV-CMOS technology (X-FAB XT018)
- Baseline: 16-bit DAC in 130 nm TSMC and current mirror to HV-CMOS HF switch
- Like to have ideal exponential pulse shape at all amplitudes → find balance between ringing and parasitic signals



- Switch and DAC test chips have been submitted and first results expected soon
- Radiation tests are in preparation

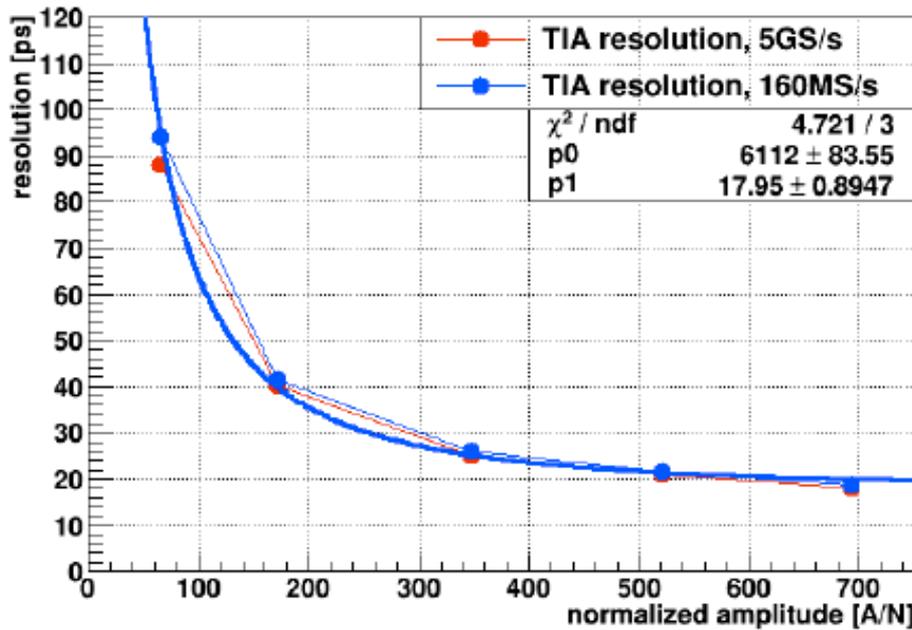
- All new front-end electronics rely on a similar powering concept
- Radiation and magnetic field tolerance is required for on-detector power devices
- Main ACDC converters for 200 V - 400 V
 - CMS EB: Maraton PS 400 V
 - ATLAS: 200 V (Tile) and 280 V (or similar, LAr)
- LVPS from 200V-400V to 12 V or 24 V or 48 V or 10 V
 - most DCDC converter developments in collaboration with industry (CAEN, Wiener)
 - located in better accessible area → long(er) power cables → noise? small diameter
 - redundancy:
 - 2 or 3 modules including 1 spare to be turned on remotely/automatically
 - power bricks running in parallel
- on front-end 2.5 V - 7.5 V local voltage
 - PoL converter and linear regulators

example: ATLAS Tile
LV power scheme



- All main calorimeters will be read out at 40 MHz motivated by new trigger systems
 - CMS ECAL includes precision time measurement
- Different front-end electronics because of: different preamp/shaper solutions, different optimal sampling rate, different radiation requirements
- Common hardware will be used for data transmission and detector control:
 - IpGBT, GBT, VL+
 - ELMB++
- Possible common solutions for LV powering:
 - PoL regulators, LVPS, ACDC main converters
- Would be nice to have:
 - radiation tolerant optical links beyond 10 Gbps → fewer FE fibers, better match to payload, more demanding FPGA requirements in data processing and buffering
- More ACES contributions on calorimeter electronics:
 - Preamplifier/Shapers and ADC for Calorimeters: Philippe Schwemmling Wednesday 15h30
 - Power Requirements and Developments for Calorimeters: Sergei Lusin Thursday 9h30
 - Thursday noon/afternoon: all on ATCA boards and infrastructure

	TID (kGy)	NIEL (n_{eq}/cm^2)	SEE (h/cm ²)
ATLAS LAr	2.3	4.9×10^{13}	7.7×10^{12}
CMS EB	10		$\sim 10^{13}$
ATLAS Tile	0.2	6×10^{12}	1.5×10^{12}



- discrete-component trans-impedance amplifier

Q is the number of electrons
APD ($\epsilon \approx 0.1$)

F is the excess noise factor

M the gain of the APD.

$$\sigma_Q = \sqrt{\frac{\Delta t \times I_{\text{leak}}}{q_e} [\epsilon + MF(1 - \epsilon)]}$$

$\sigma_Q \sim \text{sqrt}(\text{leakage current} \times \text{integration time})$

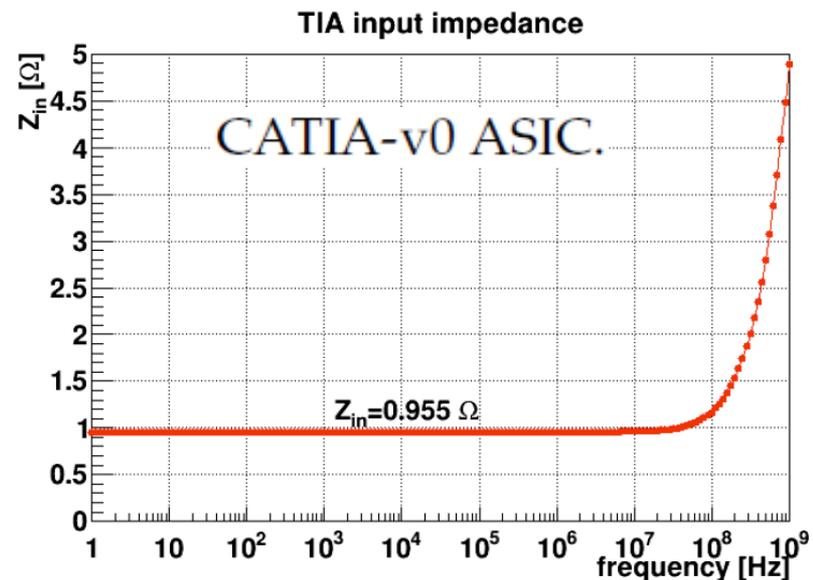
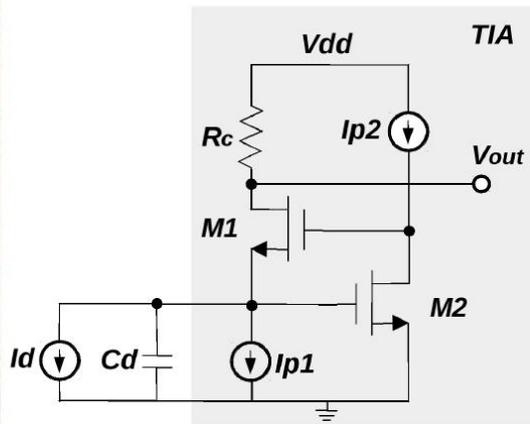
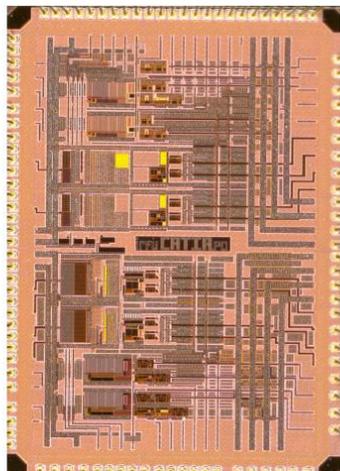
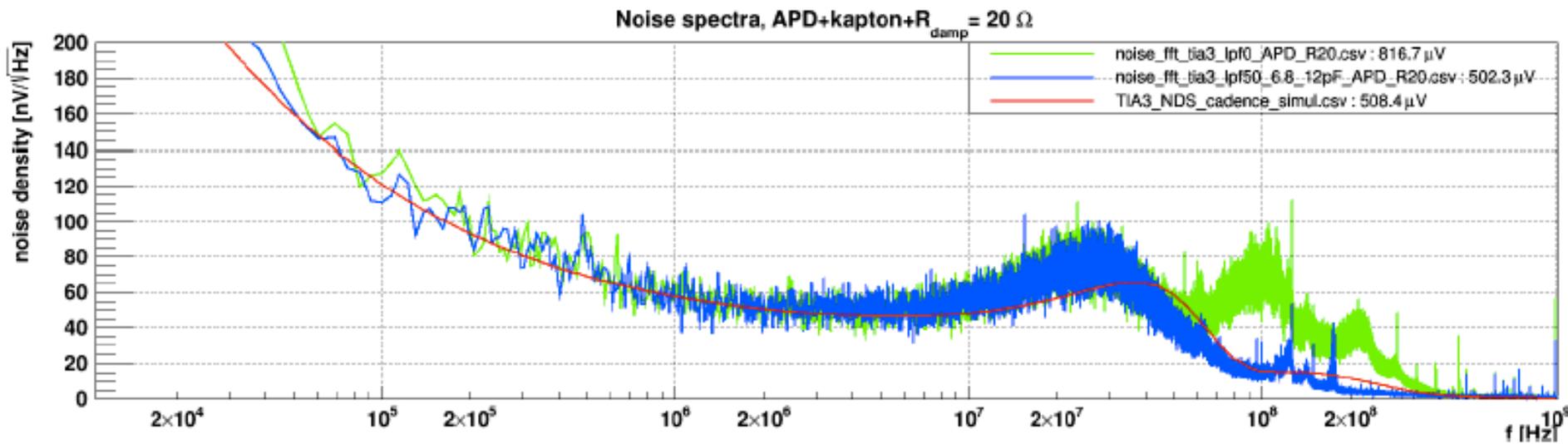
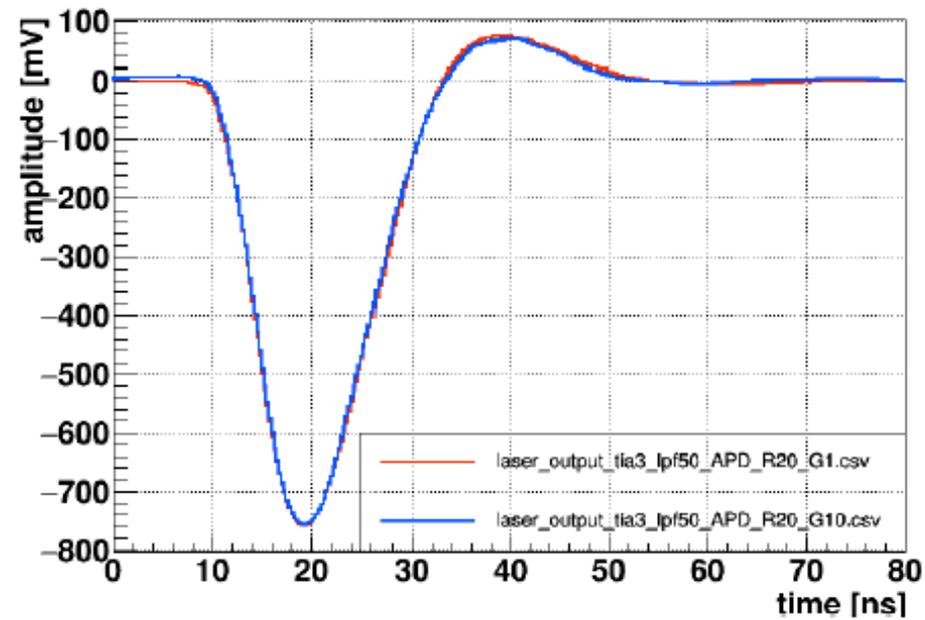


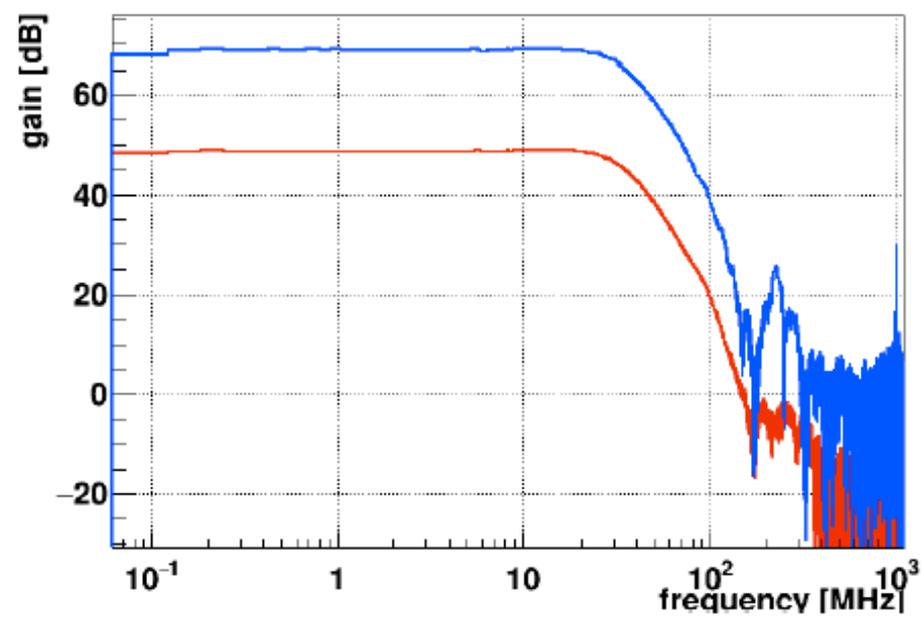
Figure 3.9: Microphotograph of the CATIA ASIC (left), and schematic view of the TIA architecture (right). See text for explanations.



TIA3 : sub-ns laser response G1 (Red), G10 (Blue)



TIA3 : sub-ns laser response spectrum G1 (Red), G10 (Blue)



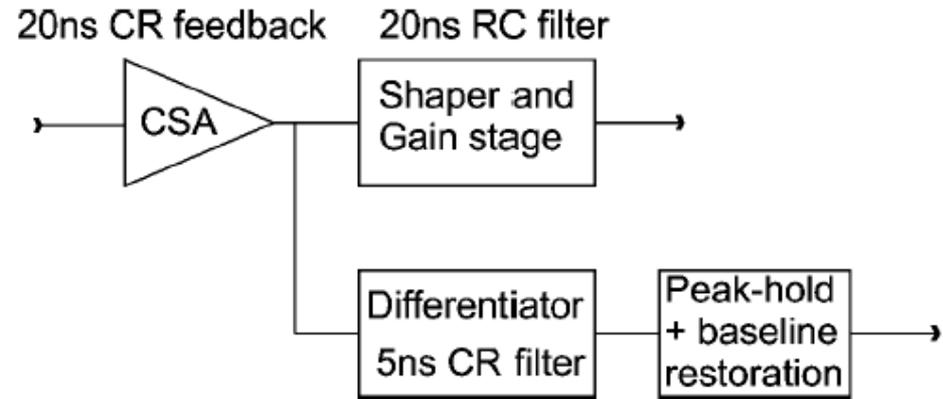
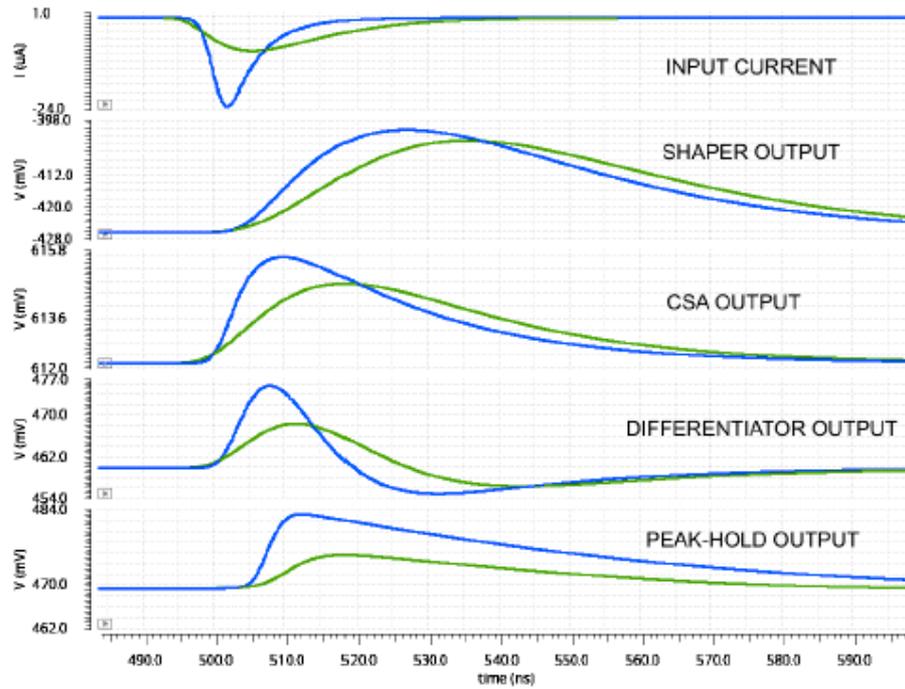
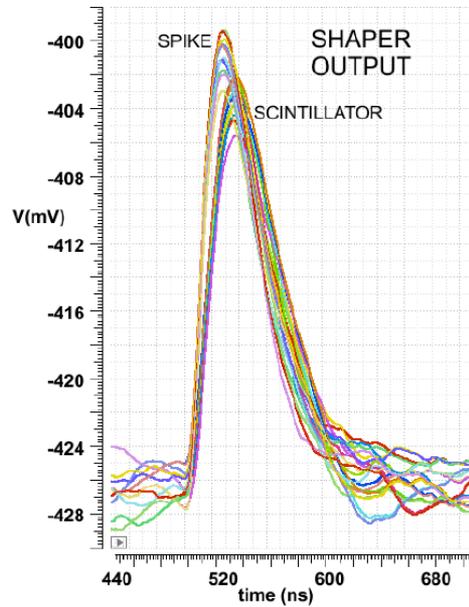
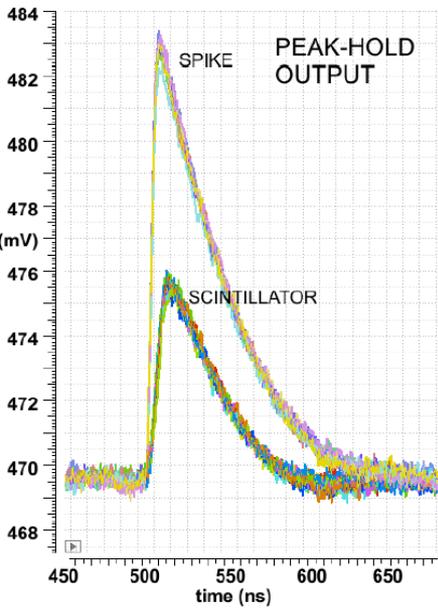


Figure 3.13: Left: MGPA++ simulation. Spike pulses are in blue, and scintillation pulses are in green. Right : MGPA++ preamplifier, shaper, and differentiator arrangement.



- on-chip spike detection not robust enough in all amplitude ranges
- off-detector spike identification preferred

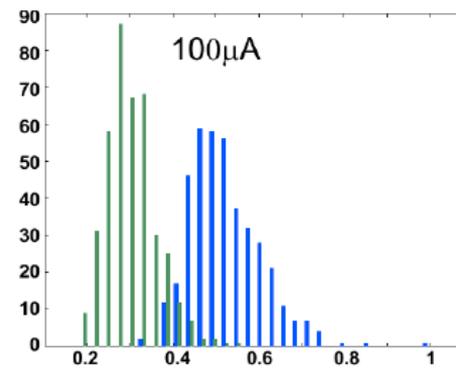
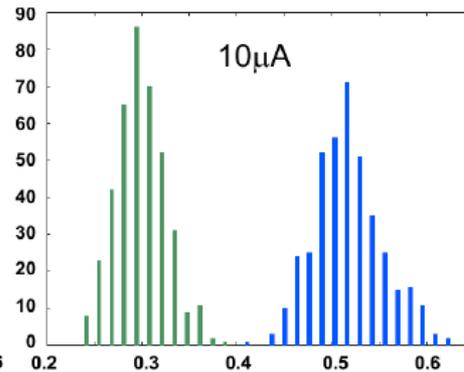
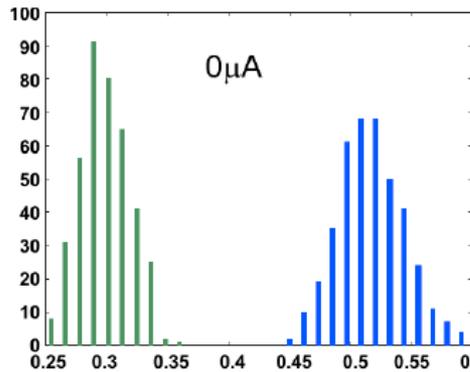


Figure 3.15: Peak-hold/shaper ratios for spikes and scintillation pulses at 2 GeV, for 0, 10, $100 \mu\text{A}$ detector leakage currents.

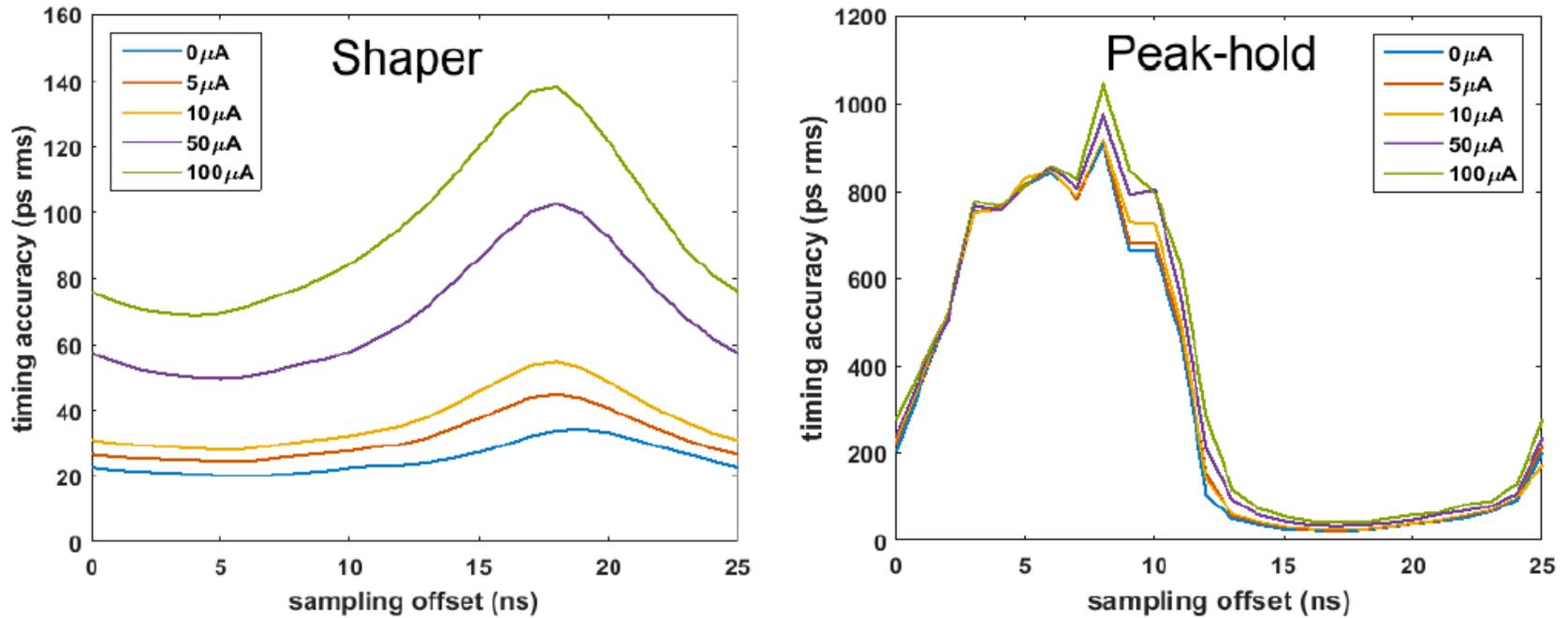
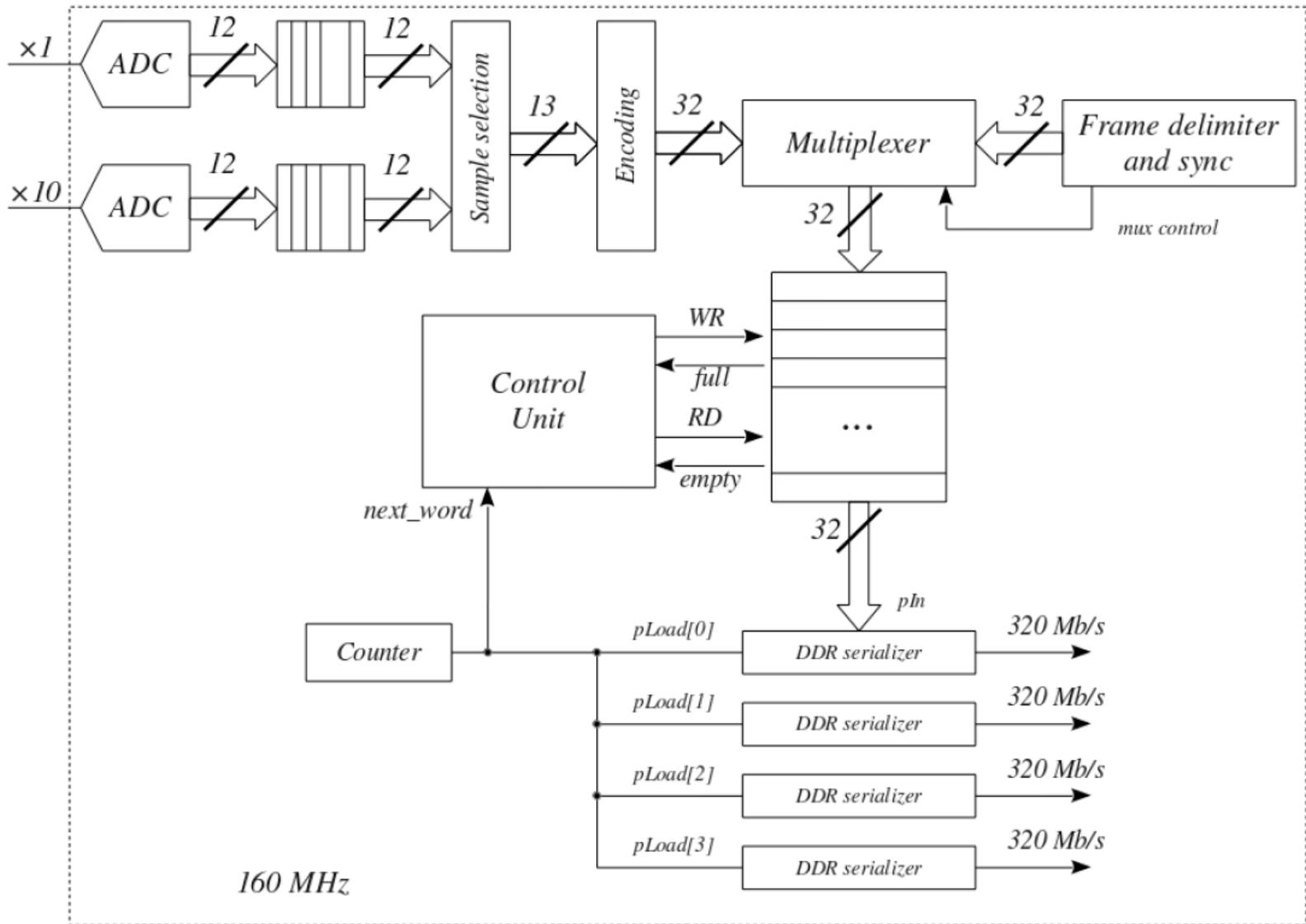


Figure 3.16: Timing accuracy for the shaper (left) and the peak-hold (right) circuits, for detector leakage currents from 0 to 100 μA .

Table 3.2: ADC requirements.

Specification	min	typ	max	unit
Sampling frequency	160			MS/s
Resolution	12			bit
Supply voltage	1.08	1.2	1.32	V
Differential input range	± 500			mV
Analogue input bandwidth	70	80		MHz
Slew rate	100			V/ μ s
Sampling clock jitter		2	5	ps
Power consumption		25	30	mW
Temperature range	-20	8	85	$^{\circ}$ C
INL		1	1.5	LSB
DNL		0.5	0.9	LSB
ENOB	10.2			bit
SNDR	63			dB
Latency		10		Clock cycles
Calibration time		100		μ s
Technology	CMOS 65 nm			
Radiation tolerance (TID)	100			kGy
SEU cross section	15 (tbc)			MeV cm ² /mg



- probability for energy value with >6 bit is 2×10^{-4} : baseline bandwidth of 2 Gbps/channel can be reduced to 1 Gbps + few Mbps for signal energies

“Baseline” data format	01	6 bits sample	6 bits sample	6 bits sample	6 bits sample	6 bits sample
“Baseline” data format 1	10	sample map	6 bits sample/00	6 bits sample/00	6 bits sample/00	6 bits sample
“Signal” data format	001010	13 bits sample		13 bits sample		
“Signal” data format 1	001011	0101010101010		13 bits sample		
Frame delimiter	1101	8 bits #samples	CRC12		8 bits frame #	
Idle pattern	1110	101010101010				

Figure 3.18: Proposed data format.

- L1 trigger primitives: either 16-bit data per crystal or per 5x5 tower

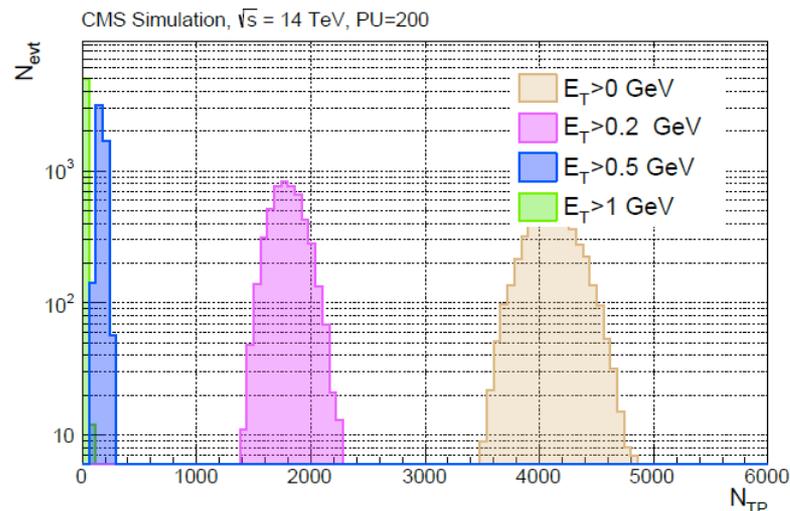


Figure 3.29: Distribution of the number of single crystal trigger primitives expected per event for several cluster E_T thresholds and a pileup level of 200 events.

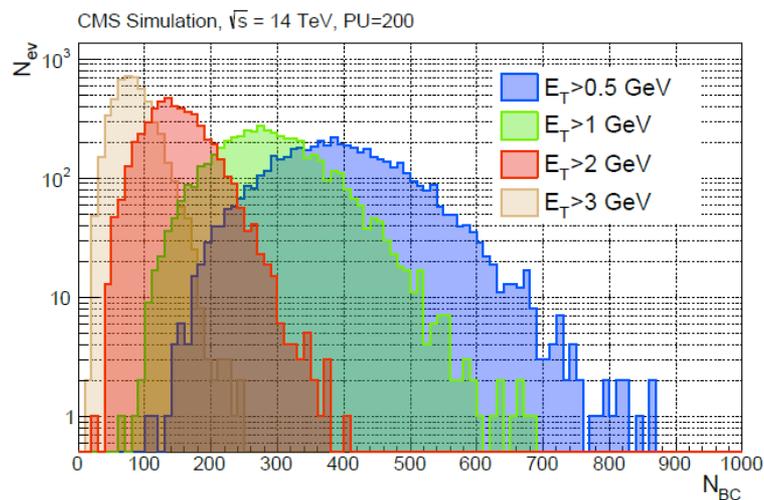
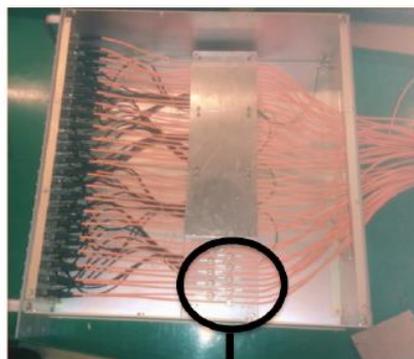
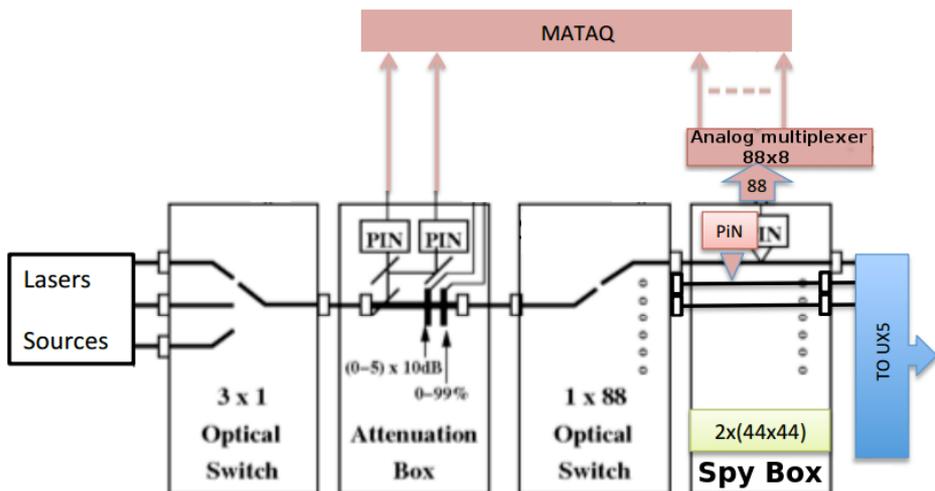


Figure 3.30: Distribution of the number of cluster trigger primitives expected per event for several cluster E_T thresholds and a pileup level of 200 events

- Energy and timing calibration and inter-calibration needed: new laser system and PiN diode light control system
- Light readout with GSample/s MATAQ chip



2 "SpyBoxes" with 44 fibres each

